

General Description

The MAX14979E is optimized for high-speed differential switching applications. The device is ideal for low-voltage differential signal (LVDS) and low-voltage positive emitter-coupled logic (LVPECL) switching applications. The MAX14979E provides enhanced electrostatic discharge (ESD) protection up to ±15kV and excellent highfrequency response, making this device especially useful for interfaces that must go to an outside connection.

The MAX14979E provides extremely low capacitance (CON) as well as low resistance (RON) for low-insertion loss and bandwidth up to 650MHz (1.3Gbps). In addition to the four pairs of double-pole/double-throw (DPDT) switches, the MAX14979E provides low-frequency (up to 50MHz) and AUX switching that can be used for LED lighting or other applications.

The MAX14979E is available in a space-saving 36-pin TQFN package and operates over the standard -40°C to +85°C temperature range.

Applications

Notebook Computers Switch LVDS to Graphics Panels LVDS and LVPECL Switching

Ordering Information

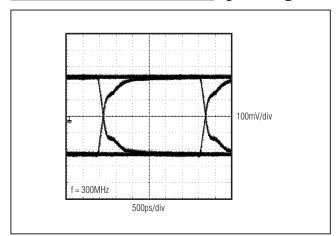
PART	TEMP RANGE	PIN-PACKAGE	
MAX14979EETX+	-40°C to +85°C	36 TQFN-EP*	

⁺Denotes a lead(Pb)-free/RoHS-compliant package.

Features

- ◆ ±15kV ESD Protected per MIL-STD-883, Method 3015
- ♦ Single +3.0V to +3.6V Power-Supply Voltage
- Low On-Resistance (RoN): 4Ω (typ), 6.5Ω (max)
- ◆ Low On-Capacitance (Con): 8pF (typ)
- → -23dB Return Loss (100MHz)
- → -3dB Bandwidth: 650MHz
- Built-In AUX Switches for Switching Indicators
- ♦ Low 450µA (max) Quiescent Current
- ♦ Bidirectional 8 to 16 Multiplexer/Demultiplexer
- ◆ Space-Saving, Lead-Free, 36-Pin, 6mm x 6mm **TQFN Package**

Eve Diagram



Typical Operating Circuit appears at end of data sheet.

^{*}EP = Exposed pad.

ABSOLUTE MAXIMUM RATINGS

(Voltages referenced to GND.)	
V+	0.3V to +4.0V
All Other Pins	0.3V to $(V + + 0.3V)$
Continuous Current (COM to NC	_/NO) ±120mA
Continuous Current (AUX0_ to AUX1_	/AUX2_)±40mA
Peak Current (COM to NC/NO_	_)
(pulsed at 1ms, 10% duty cycle)	±240mA
Current into Any Other Pin	±20mA

Continuous Power Dissipation ($T_A = +70^{\circ}C$)	
36-Pin TQFN (derate 35.7mW/°C above +70°C)2.85mV	Ν
Operating Temperature Range40°C to +85°C	С
Junction Temperature+150°C	С
Storage Temperature Range65°C to +150°C	С
Lead Temperature (soldering 10s)+300°	С
Soldering Temperature (reflow)+260°	С

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

PACKAGE THERMAL CHARACTERISTICS (Note 1)

TOFN

Junction-to-Ambient Thermal Resistance (θ_{JA})......8°C/W Junction-to-Case Thermal Resistance (θ_{JC}).............1°C/W

Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maxim-ic.com/thermal-tutorial.

ELECTRICAL CHARACTERISTICS

 $(V + = +3.0V \text{ to } +3.6V, T_A = T_J = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$ Typical values are at $V + = +3.3V, T_A = +25^{\circ}C.$) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	3	MIN	TYP	MAX	UNITS
POWER SUPPLIES							
Operating Power-Supply Range	V+			+3.0		+3.6	V
ANALOG SWITCH							
On-Resistance	Ron	$V + = 3V, ICOM_{-} = -40mA,$	$T_A = +25^{\circ}C$		4	5.5	Ω
OTFITESISTATICE	TION	VCOM = 0V, 1.5V, 3V	TMIN to TMAX			6.5	
On-Resistance AUX Switches	RONAUX	V+ = 3V, I _{AUX0} = -40mA, V ₂ 1.5V, 3V	AUX0_ = 0V,			40	Ω
On-Resistance Match	ADON	V+ = 3V, I _{COM} = -40mA,	T _A = +25°C		0.5	1.5	Ω
Between Channels	ΔRon	VCOM = 0V, 3V (Note 3)				2	1 12
On-Resistance Flatness	RFLAT(ON)	V+ = 3V, I _{COM} _ = -40mA, V _{COM} _ = 0V, 1.5V			0.01		Ω
Off-Leakage Current	ILCOM_ _(OFF)	V+ = 3.6V, V _{COM} _ = 0.3V, 3.3V; V _{NC} _ or V _{NO} _ = 3.3V, 0.3V		-1		+1	μА
On-Leakage Current	ILCOM_ _(ON)	V+ = 3.6V, V _{COM} _ = 0.3V, 3.3V; V _{NC} _ or V _{NO} _ = 3.3V, 0.3V or unconnected		-1		+1	μА
SWITCH AC PERFORMANCE	•						
Insertion Loss	ILOS	$R_S = R_L = 50\Omega$, unbalanced (Note 3)	$R_S = R_L = 50\Omega$, unbalanced, $f = 1MHz$, (Note 3)		0.6		dB
Return Loss	RLOS	f = 100MHz			-23		dB
Crosstalk	VCT1	Any switch to any switch; $R_S = R_L = 50\Omega$.	, , , , , , , , , , , , , , , , , , , ,		-50		dB
O TOO CLAIR	VCT2	unbalanced, Figure 1	f = 125MHz		-26		d B
SWITCH AC CHARACTERISTICS							
-3dB Bandwidth	BW	$R_S = R_L = 50\Omega$, unbalanced			650		MHz
Off-Capacitance	Coff	f = 1MHz, COM			3.5		pF
On-Capacitance	Con	f = 1MHz, COM			8		pF

ELECTRICAL CHARACTERISTICS (continued)

 $(V+ = +3.0V \text{ to } +3.6V, T_A = T_J = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$ Typical values are at $V+ = +3.3V, T_A = +25^{\circ}C.$) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Turn-On Time	ton	$V_{COM} = 1V$, $R_L = 100\Omega$, Figure 2			50	ns
Turn-Off Time	toff	$V_{COM} = 1V$, $R_L = 100\Omega$, Figure 2			50	ns
Propagation Delay	tplh, tphl	$R_S = R_L = 50\Omega$, unbalanced, Figure 3		0.1		ns
Output Skew Between Ports	tSK(o)	Skew between any two ports, Figure 4		0.01		ns
SWITCH LOGIC						
Input-Voltage Low	VIL	V+ = 3.0V			0.8	V
Input-Voltage High	VIH	V+ = 3.6V	2.0			V
Input-Logic Hysteresis	VHYST	V+ = 3.3V		100		mV
Input Leakage Current	ISEL	V+ = 3.6V, V _{SEL} = 0V or V+	-5		+5	μΑ
Quiescent Supply Current	l+	V+ = 3.6V, VSEL = 0V or V+		280	450	μΑ
ESD PROTECTION						
ESD Protection		COM, NC, NO HBM (spec MIL-STD-883, Method 3015)		±15		kV
All Other Pins		HBM (spec MIL-STD-883, Method 3015)		±2		kV

Note 2: Specifications at $TA = -40^{\circ}C$ are guaranteed by design.

Note 3: Guaranteed by design.

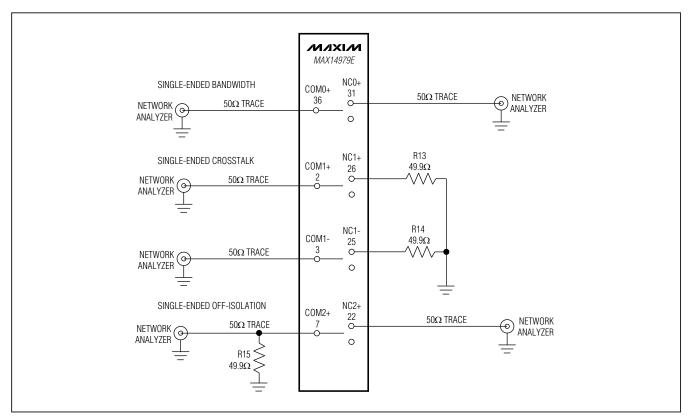


Figure 1. Single-Ended Bandwidth, Crosstalk, and Off-Isolation

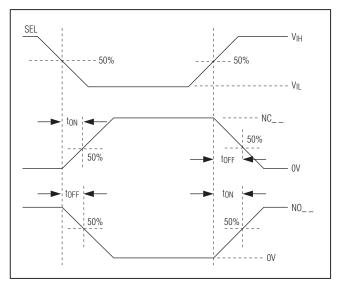


Figure 2. Turn-On and Turn-Off Times

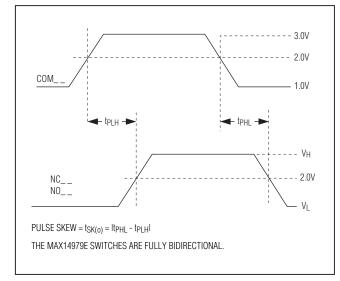


Figure 3. Propagation Delay Times

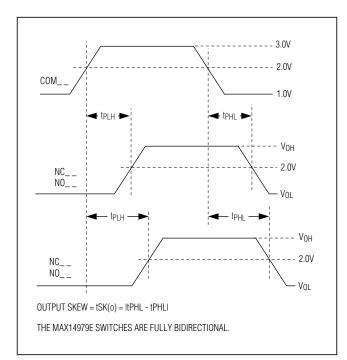
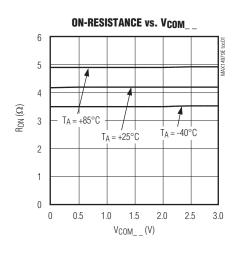
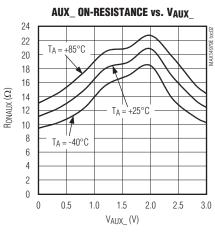


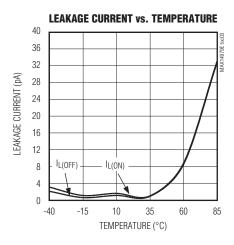
Figure 4. Output Skew

Typical Operating Characteristics

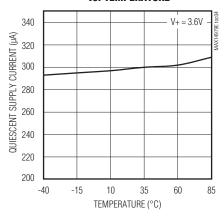
 $(V+ = 3.3V, T_A = +25^{\circ}C, unless otherwise noted.)$



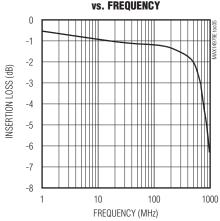




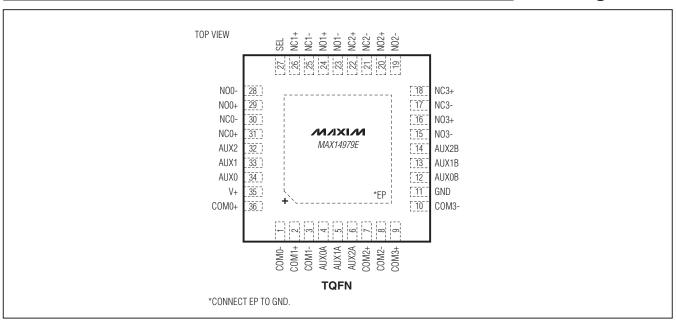
QUIESCENT SUPPLY CURRENT vs. TEMPERATURE



SINGLE-ENDED INSERTION LOSS vs. Frequency



Pin Configuration



Pin Description

PIN	NAME	FUNCTION
1	COM0-	Common LVDS Differential Terminal for Switch 0
2	COM1+	Common LVDS Differential Terminal for Switch 1
3	COM1-	Common LVDS Differential Terminal for Switch 1
4	AUX0A	AUX0A Input
5	AUX1A	AUX1A Output. Drive SEL low (SEL = 0) to connect AUX0A to AUX1A.
6	AUX2A	AUX2A Output. Drive SEL high (SEL = 1) to connect AUX0A to AUX2A.
7	COM2+	Common LVDS Differential Terminal for Switch 2
8	COM2-	Common LVDS Differential Terminal for Switch 2
9	COM3+	Common LVDS Differential Terminal for Switch 3
10	COM3-	Common LVDS Differential Terminal for Switch 3
11	GND	Ground
12	AUX0B	AUX0B Input
13	AUX1B	AUX1B Output. Drive SEL low (SEL = 0) to connect AUX0B to AUX1B.
14	AUX2B	AUX2B Output. Drive SEL high (SEL = 1) to connect AUX0B to AUX2B.
15	NO3-	Normally Open LVDS Differential Terminal for Switch 3
16	NO3+	Normally Open LVDS Differential Terminal for Switch 3
17	NC3-	Normally Closed LVDS Differential Terminal for Switch 3
18	NC3+	Normally Closed LVDS Differential Terminal for Switch 3
19	NO2-	Normally Open LVDS Differential Terminal for Switch 2
20	NO2+	Normally Open LVDS Differential Terminal for Switch 2
21	NC2-	Normally Closed LVDS Differential Terminal for Switch 2

Pin Description (continued)

PIN	NAME	FUNCTION
22	NC2+	Normally Closed LVDS Differential Terminal for Switch 2
23	NO1-	Normally Open LVDS Differential Terminal for Switch 1
24	NO1+	Normally Open LVDS Differential Terminal for Switch 1
25	NC1-	Normally Closed LVDS Differential Terminal for Switch 1
26	NC1+	Normally Closed LVDS Differential Terminal for Switch 1
27	SEL	Select Input. SEL selects switch connection. See Table1.
28	NO0-	Normally Open LVDS Differential Terminal for Switch 0
29	NO0+	Normally Open LVDS Differential Terminal for Switch 0
30	NC0-	Normally Closed LVDS Differential Terminal for Switch 0
31	NC0+	Normally Closed LVDS Differential Terminal for Switch 0
32	AUX2	AUX2 Output. Drive SEL high (SEL = 1) to connect AUX0 to AUX2.
33	AUX1	AUX1 Output. Drive SEL low (SEL = 0) to connect AUX0 to AUX1.
34	AUX0	AUX0 Input
35	V+	Positive-Supply Voltage Input. Bypass V+ to GND with a 0.1µF ceramic capacitor.
36	COM0+	Common LVDS Differential Terminal for Switch 0
_	EP	Exposed Pad. Connect exposed pad to GND or leave it unconnected.

Detailed Description

The MAX14979E is a high-speed analog switch targeted at LVDS and other low-voltage switching up to 600MHz. In a typical application, the MAX14979E switches two sets of LVDS sources to a laptop LVDS panel. For extra security, the MAX14979E is protected against ±15kV ESD shocks. See the *Functional Diagram*.

With its low resistance and capacitance, as well as high-ESD protection, the MAX14979E can be used to switch most low-voltage differential signals, such as LVDS and LVPECL, as long as the signals do not exceed the maximum ratings of the device.

The MAX14979E switches provide low capacitance and on-resistance to meet low insertion loss and return-loss specifications. The MAX14979E has three additional AUX switches.

Digital Control Inputs

The MAX14979E provides a single digital control SEL. SEL controls the switches as well as the AUX switches, as shown in Table 1.

Analog-Signal Levels

The on-resistance of the MAX14979E is very low and stable as the analog input signals are swept from ground to V+ (see the *Typical Operating Characteristics*). The

switches are bidirectional, allowing COM_ $_$ and NC_ $_/$ NO_ $_$ to be configured as either inputs or outputs.

ESD Protection

The MAX14979E is characterized using the HBM for $\pm 15 \text{kV}$ of ESD protection. Figure 5 shows the HBM. This model consists of a 100pF capacitor charged to the ESD voltage of interest, which is then discharged into the test device through a $1.5 \text{k}\Omega$ resistor. All signal and control pins are ESD protected to $\pm 15 \text{kV}$ HBM.

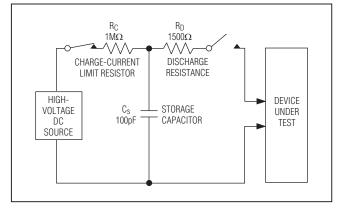


Figure 5. Human Body ESD Test Model (MIL-STD-883, Method 3015)

Functional Diagram

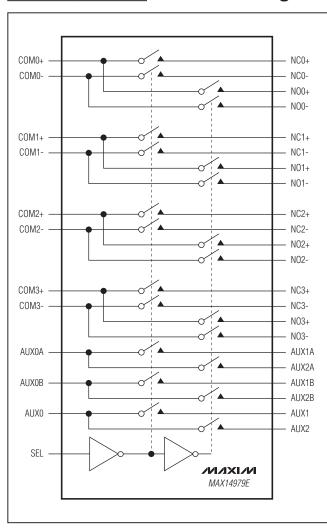


Table 1. Truth Table

SEL	CONNECTION			
0	COM_ to NC_ , AUX0_ to AUX1_			
1	COM_ to NO_ , AUX0_ to AUX2_			

Applications Information

Typical Operating Circuit

The *Typical Operating Circuit* shows the MAX14979E in a dual graphics application.

Power-Supply Sequencing and Overvoltage Protection

Caution: Do not exceed the absolute maximum ratings. Stresses beyond the listed ratings may cause permanent damage to the device.

Proper power-supply sequencing is recommended for all CMOS devices. Always apply V+ before applying analog signals, especially if the analog signal is not current limited.

Layout

High-speed switches require proper layout and design procedures for optimum performance. Keep design-controlled-impedance PCB traces as short as possible. Ensure that bypass capacitors are as close as possible to the device. Use large ground planes where possible.

Chip Information

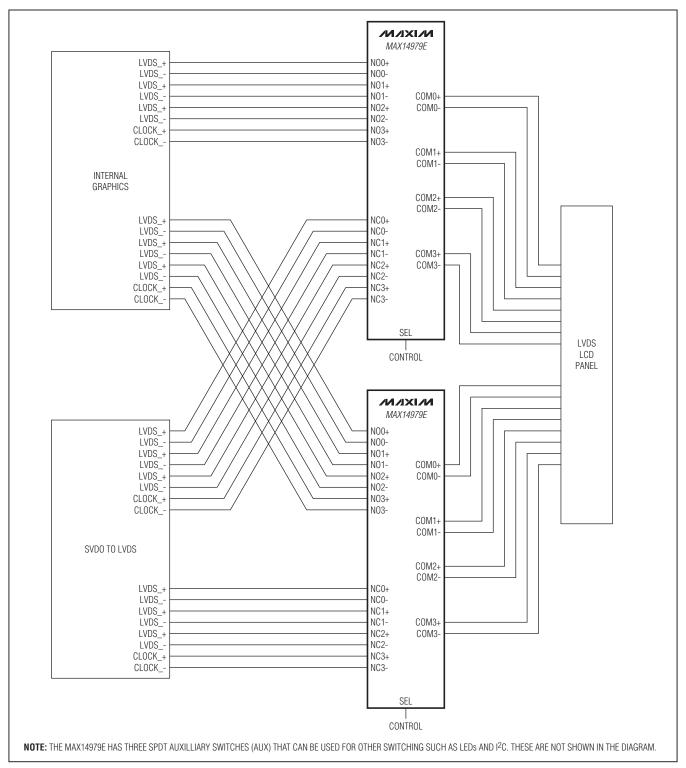
PROCESS: BiCMOS

Package Information

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE	PACKAGE	OUTLINE	LAND
TYPE	CODE	NO.	PATTERN NO.
36 TQFN-EP	T3666+3	21-0141	

Typical Operating Circuit



Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	4/10	Initial release	_
1	6/11	Updated Package Thermal Characteristics style; corrected Pin Configuration and Pin Description for AUX1_ and AUX2_ pins	2, 6

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.